

CPW4-1200-S005B Silicon Carbide Schottky Diode Chip Z-REC $^{\oplus}$ RECTIFIER

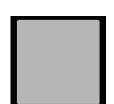
 $\mathbf{V}_{RRM} = 1200 \,\mathrm{V}$ $\mathbf{I}_{F} = 5 \,\mathrm{A}$

27 nC

Q

Features Chip Outline

- 1.2kVSchottky Rectifier
- · Zero Reverse Recovery
- Zero Forward Recovery
- High-Frequency Operation
- Temperature-Independent Switching Behavior
- · Extremely Fast Switching
- Positive Temperature Coefficient on V_E



Part Number	Die Size	Anode	Cathode
CPW4-1200-S005B	1.69 x 1.69 mm ²	Al	Ni/Ag

Maximum Ratings

Symbol	Parameter	Value	Unit	Test Conditions	Note
V _{RRM}	Repetitive Peak Reverse Voltage	1200	٧		
V _{RSM}	Surge Peak Reverse Voltage	1300	٧		
V _R	DC Peak Blocking Voltage	1200	٧		
I _F	Continuous Forward Current	5	А	T _J =175°C	1
I _{FRM}	Repetitive Peak Forward Surge Current	26 18	А	T_c =25°C, t_p =10 ms, Half Sine Pulse T_c =110°C, t_p =10 ms, Half Sine Pulse	1
I _{FSM}	Non-Repetitive Forward Surge Current	46 36	А	T_c =25°C, t_p =10 ms, Half Sine Pulse T_c =110°C, t_p =10 ms, Half Sine Pulse	1
I _{F,Max}	Non-Repetitive Peak Forward Current	400 320	А	T _c =25°C, t _p =10 μs, Pulse T _c =110°C, t _p =10 μs, Pulse	
T _J , T _{stg}	Operating Junction and Storage Temperature	-55 to +175	°C		
T _{Proc}	Maximum Processing Temperature	325	°C	10 min. maximum	

^{1.} Assumes R_{e,JC} Thermal Resistance of 1.85°C/W or less



Electrical Characteristics

Symbol	Parameter	Тур.	Max.	Unit	Test Conditions	Note
V _F	Forward Voltage	1.4 1.9	1.8 3	٧	I _F = 5 A T _J =25°C I _F = 5 A T _J =175°C	Fig. 1
I _R	Reverse Current	20 40	150 300	μA	V _R = 1200 V T _J =25°C V _R = 1200 V T _J =175°C	Fig. 2
Q_c	Total Capacitive Charge	27		nC	$V_R = 800 \text{ V, } I_F = 5A$ $di/dt = 200 \text{ A/}\mu\text{s}$ $T_J = 25^{\circ}\text{C}$	Fig. 3
С	Total Capacitance	390 27 20		pF	V _R = 0 V, T _J = 25°C, f = 1 MHz V _R = 400 V, T _J = 25°C, f = 1 MHz V _R = 800 V, T _J = 25°C, f = 1 MHz	Fig. 4

Mechanical Parameters

Parameter	Тур.	Unit
Die Size	1.69 x 1.69	mm
Anode Pad Size	1.40 x 1.40	mm
Anode Pad Opening	1.12 x 1.12	mm
Thickness	377 ± 10%	μm
Wafer Size	100	mm
Anode Metalization (AI)	4	μm
Cathode Metalization (Ni/Ag)	1.4	μm
Frontside Passivation	Polyimide	



Typical Characteristics

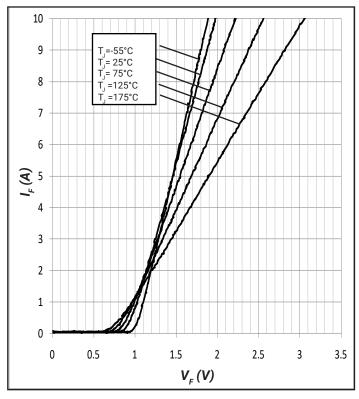


Figure 1. Forward Characteristics

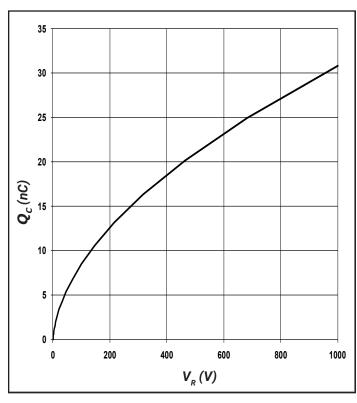


Figure 3. Total Capacitance Charge vs. Reverse Voltage

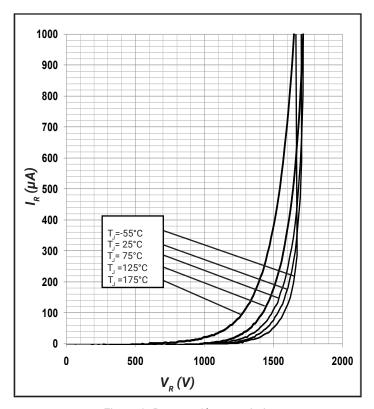


Figure 2. Reverse Characteristics

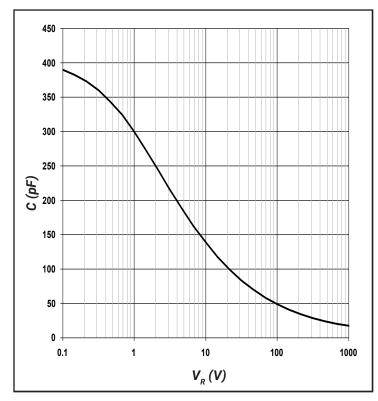
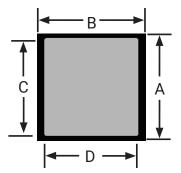


Figure 4. Capacitance vs. Reverse Voltage



Chip Dimensions



symbol	dimension			
	mm	inch		
А	1.69	0.067		
В	1.69	0.067		
С	1.12	0.044		
D	1.12	0.044		

Notes

RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented January 2, 2013. RoHS Declarations for this product can be obtained from your Cree representative or from the Product Documentation sections of www.cree.com.

REACh Compliance

REACh substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a Cree representative to insure you get the most up-to-date REACh SVHC Declaration. REACh banned substance information (REACh Article 67) is also available upon request.

• This product has not been designed or tested for use in, and is not intended for use in, applications implanted into the human body nor in applications in which failure of the product could lead to death, personal injury or property damage, including but not limited to equipment used in the operation of nuclear facilities, life-support machines, cardiac defibrillators or similar emergency medical equipment, aircraft navigation or communication or control systems, or air traffic control systems.

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